

overlapping said edge of said first substrate with said edge of said second substrate;

positioning a continuous thermoplastic tape having a first tape portion and a second tape portion adjacent to said first substrate and said second substrate such that said first tape portion is in operative communication with said upper and lower surfaces of said first substrate and said second tape portion is in operative communication with said upper and lower surfaces of said second substrate; and

forming an adhesive bond and a physical bond between said first tape portion and said first substrate and between said second tape portion and said second substrate.

B1
B2
19. (Amended) A method as defined in claim 1, further comprising etching at least one of said surfaces of said first substrate.

20. (Amended) A method as defined in claim 1, further comprising etching at least one of said surfaces of said second substrate.

B3
22. (Amended) A method of forming a seam between substrates comprising:
providing a first substrate having an upper surface and a lower surface, said upper and said lower surfaces of said first substrate defining at least one edge;
providing a second substrate having an upper surface and a lower surface, said upper and said lower surfaces of said second substrate defining at least one edge;
overlapping said edge of said first substrate with said edge of said second substrate;

positioning a continuous thermoplastic tape having a first tape portion and a second tape portion adjacent to said first substrate and said second substrate such that

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said first tape portion is in operative communication with said upper and lower surfaces of said first substrate and said second tape portion is in operative communication with said upper and lower surfaces of said second substrate;

folding said tape into a z-shaped configuration;
subjecting said first tape portion to simultaneous heat and pressure;
subjecting said second tape portion to simultaneous heat and pressure; and
forming an adhesive bond and a physical bond between said first tape portion and said first substrate and between said second tape portion and said second substrate.

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26. (Amended) A method as defined in claim 22, further comprising etching at least one of said surfaces of said first substrate.

27. (Amended) A method as defined in claim 22, further comprising etching at least one of said surfaces of said second substrate.

29. (Amended) A seam for joining two or more substrates of an article, said seam comprising:

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a first substrate having an upper surface and a lower surface, said upper and said lower surfaces of said first substrate defining at least one edge;
a second substrate having an upper surface and a lower surface, said upper and said lower surfaces of said second substrate defining at least one edge, said edge of said second substrate overlapping said edge of said first substrate; and

a continuous thermoplastic tape having a first tape portion and a second tape portion positioned adjacent to said first substrate and said second substrate such that said first tape portion is adhesively and physically bonded to said upper and lower